

TPCP8306

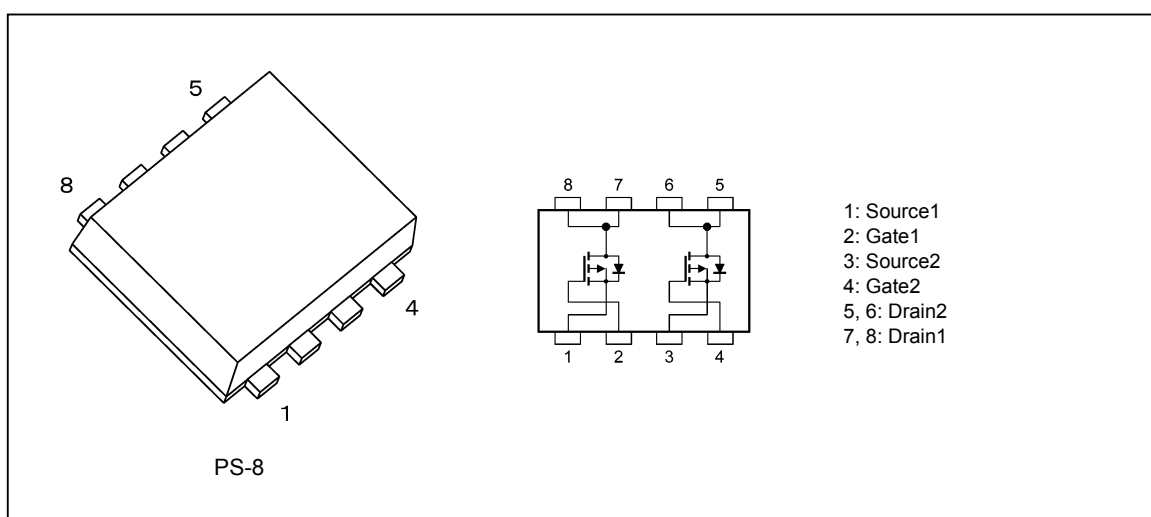
1. Applications

- Notebook PCs
- Mobile Handsets

2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 47 \text{ m}\Omega$ (typ.) ($V_{GS} = -4.5 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = -10 \text{ }\mu\text{A}$ (max) ($V_{DS} = -20 \text{ V}$)
- (4) Enhancement mode: $V_{th} = -0.5$ to -1.2 V ($V_{DS} = -10 \text{ V}$, $I_D = -0.2 \text{ mA}$)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	-20	V
Gate-source voltage	V_{GSS}	± 12	
Drain current (DC) (Note 1)	I_D	-4	A
Drain current (pulsed) (Note 1)	I_{DP}	-16	
Power dissipation (single operation) (t = 5 s) (Note 2), (Note 4)	$P_{D(1)}$	1.48	W
Power dissipation (per device for dual operation) (t = 5 s) (Note 2), (Note 5)	$P_{D(2)}$	1.23	
Power dissipation (single operation) (t = 5 s) (Note 3), (Note 4)	$P_{D(1)}$	0.58	
Power dissipation (per device for dual operation) (t = 5 s) (Note 3), (Note 5)	$P_{D(2)}$	0.36	
Single-pulse avalanche energy (Note 6)	E_{AS}	10.4	mJ
Avalanche current	I_{AR}	-4	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-ambient thermal resistance (single operation) (t = 5 s) (Note 2), (Note 4)	$R_{th(ch-a)(1)}$	84.4	$^\circ\text{C/W}$
Channel-to-ambient thermal resistance (per device for dual operation) (t = 5 s) (Note 2), (Note 5)	$R_{th(ch-a)(2)}$	101.6	
Channel-to-ambient thermal resistance (single operation) (t = 5 s) (Note 3), (Note 4)	$R_{th(ch-a)(1)}$	215.5	
Channel-to-ambient thermal resistance (per device for dual operation) (t = 5 s) (Note 3), (Note 5)	$R_{th(ch-a)(2)}$	347.2	

Note 1: Ensure that the channel temperature does not exceed 150°C .

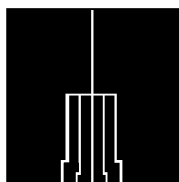
Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

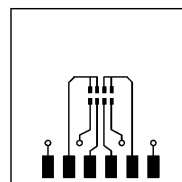
Note 4: Power dissipation and thermal resistance values per device with the other device being off (During single operation, power is supplied to only one of the two devices.)

Note 5: Power dissipation and thermal resistance values per device for dual operation (During dual operation, power is evenly supplied to both devices.)

Note 6: $V_{DD} = -16\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5\text{ mH}$, $R_G = 25\ \Omega$, $I_{AR} = -4\text{ A}$



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics ($T_a = 25^\circ\text{C}$ unless otherwise specified)

6.1. Static Characteristics

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 12\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	—	—	-10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = -10\text{ mA}, V_{GS} = 0\text{ V}$	-20	—	—	V
Drain-source breakdown voltage (Note 7)	$V_{(BR)DSX}$	$I_D = -10\text{ mA}, V_{GS} = 8\text{ V}$	-12	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = -10\text{ V}, I_D = -0.2\text{ mA}$	-0.5	—	-1.2	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = -1.8\text{ V}, I_D = -1\text{ A}$	—	125	265	$\text{m}\Omega$
		$V_{GS} = -2.0\text{ V}, I_D = -2\text{ A}$	—	95	160	
		$V_{GS} = -2.5\text{ V}, I_D = -2\text{ A}$	—	65	83	
		$V_{GS} = -4.5\text{ V}, I_D = -2\text{ A}$	—	47	58	

Note 7: If a forward bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	680	—	pF
Reverse transfer capacitance	C_{rss}		—	85	—	
Output capacitance	C_{oss}		—	108	—	
Switching time (rise time)	t_r	See Figure 6.2.1.	—	8.7	—	ns
Switching time (turn-on time)	t_{on}		—	16	—	
Switching time (fall time)	t_f		—	18	—	
Switching time (turn-off time)	t_{off}		—	70	—	

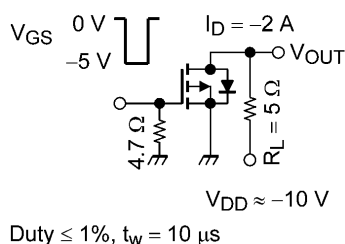


Fig. 6.2.1 Switching Time Test Circuit

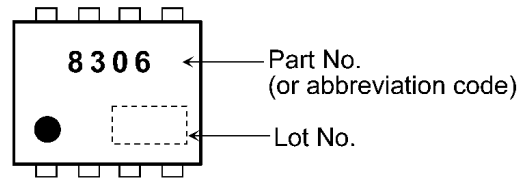
6.3. Gate Charge Characteristics

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx -16\text{ V}, V_{GS} = -5\text{ V}, I_D = -4\text{ A}$	—	9.2	—	nC
Gate-source charge 1	Q_{gs1}		—	1.8	—	
Gate-drain charge	Q_{gd}		—	2.0	—	

6.4. Source-Drain Characteristics

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Pulsed reverse drain current (Note 8)	I_{DRP}	—	—	—	-16	A
Diode forward voltage	V_{DSF}	$I_{DR} = -4\text{ A}, V_{GS} = 0\text{ V}$	—	—	1.2	V

Note 8: Ensure that the channel temperature does not exceed 150°C .

7. Marking**Fig. 7.1 Marking**

8. Characteristics Curves (Note)

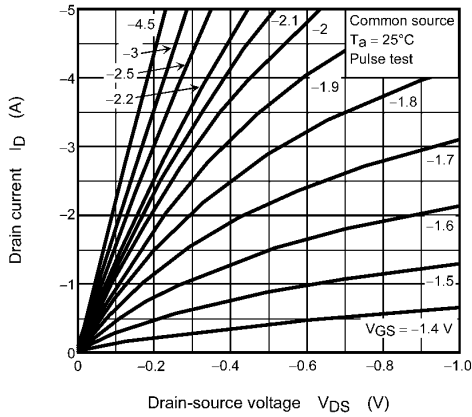


Fig. 8.1 ID - VDS

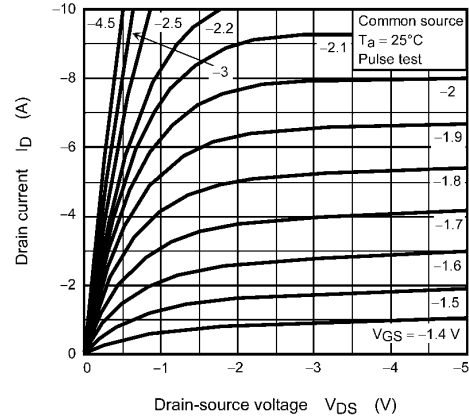


Fig. 8.2 ID - VDS

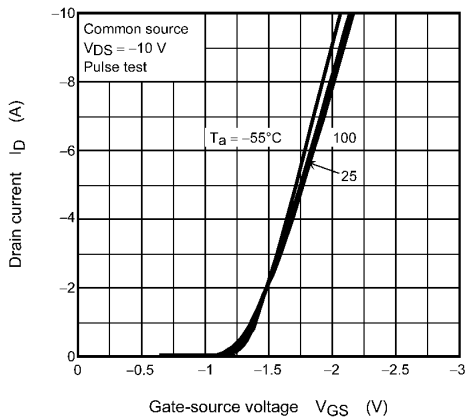


Fig. 8.3 ID - VGS

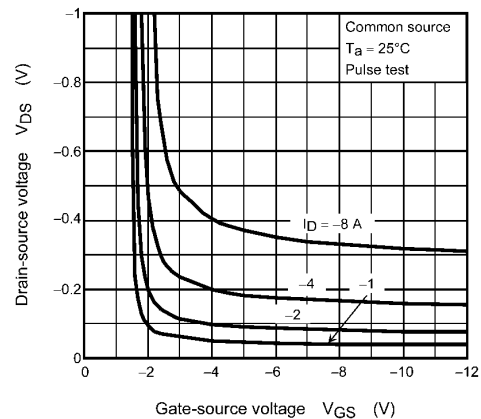


Fig. 8.4 VDS - VGS

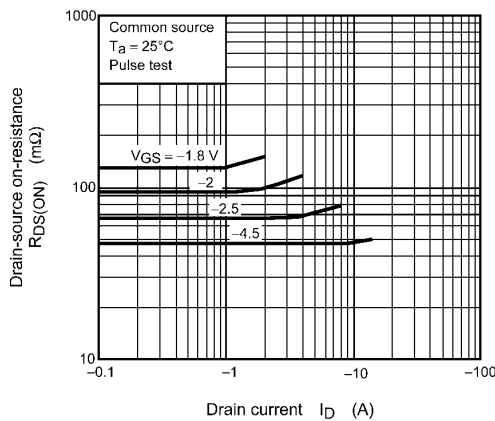


Fig. 8.5 RDS(ON) - ID

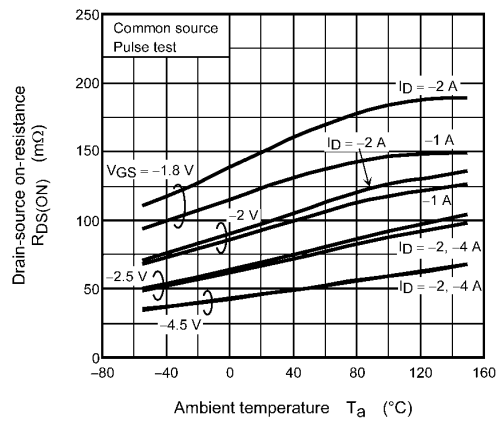


Fig. 8.6 RDS(ON) - Ta

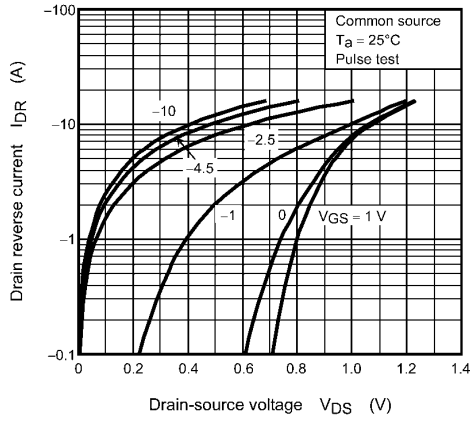


Fig. 8.7 $I_{DR} - V_{DS}$

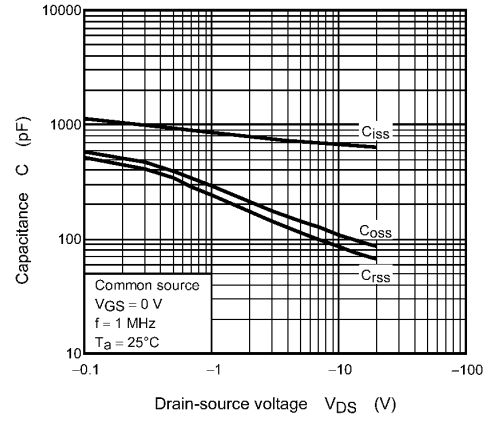


Fig. 8.8 Capacitance - V_{DS}

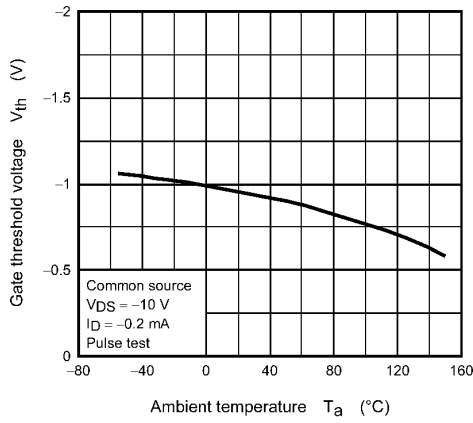


Fig. 8.9 $V_{th} - T_a$

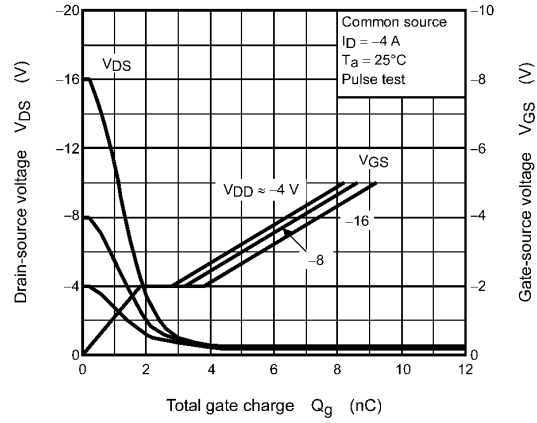


Fig. 8.10 Dynamic Input/Output Characteristics

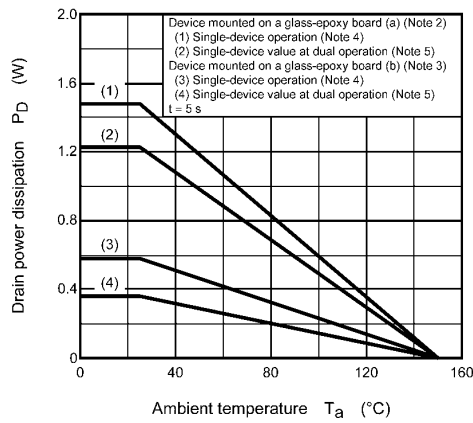


Fig. 8.11 $P_D - T_a$
 (Guaranteed Maximum)

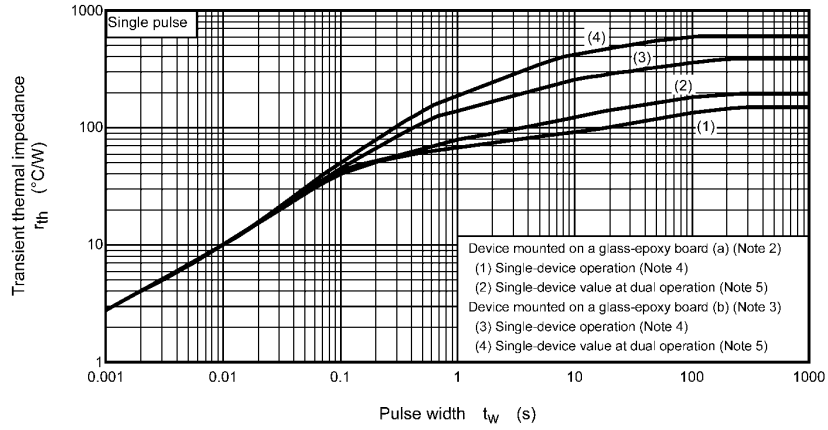


Fig. 8.12 $r_{th} - t_w$
(Guaranteed Maximum)

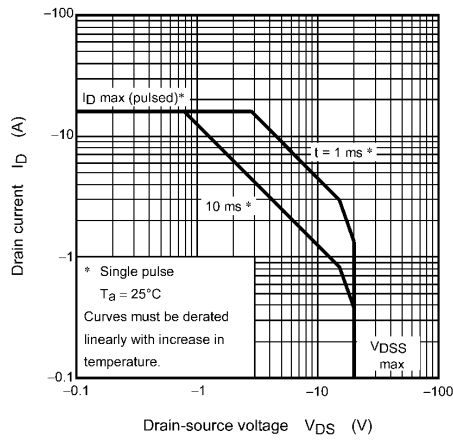
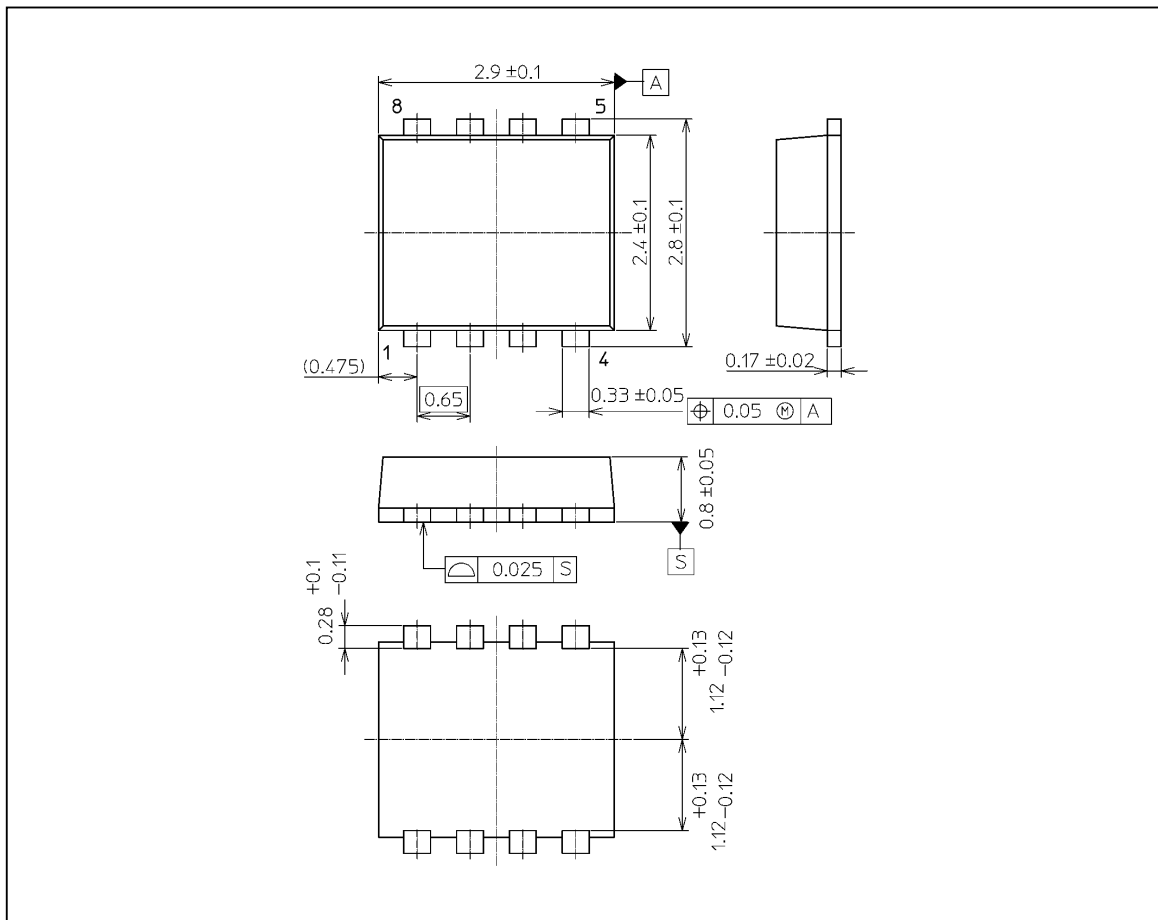


Fig. 8.13 Safe Operating Area
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)

Package Name(s)
TOSHIBA: 2-3V1S
Nickname: PS-8

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